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December 2014

#### **FDZ193P**

## P-Channel 1.7V PowerTrench® WL-CSP MOSFET

**-20V**, **-1A**, **90m**Ω

#### **Features**

- Max  $r_{DS(on)}$  = 90m $\Omega$  at  $V_{GS}$  = -4.5V,  $I_D$  = -1A
- Max  $r_{DS(on)}$  = 130m $\Omega$  at  $V_{GS}$  = -2.5V,  $I_D$  = -1A
- Max  $r_{DS(on)}$  = 300m $\Omega$  at  $V_{GS}$  = -1.7V,  $I_D$  = -1A
- Occupies only 1.5 mm<sup>2</sup> of PCB area Less than 50% of the area of 2 x 2 BGA
- Ultra-thin package: less than 0.65 mm height when mounted to PCB
- RoHS Compliant

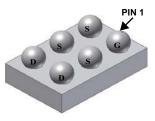


#### **General Description**

Designed on Fairchild's advanced 1.7V PowerTrench® process with state of the art "low pitch" WLCSP packaging process, the FDZ193P minimizes both PCB space and  $r_{DS(on)}$ . This advanced WLCSP MOSFET embodies a breakthrough in packaging technology which enables the device to combine excellent thermal transfer characteristics, ultra-low profile packaging, low gate charge, and low  $r_{DS(on)}$ .

#### **Application**

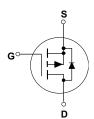
- Battery management
- Load switch
- Battery protection







TOP



### MOSFET Maximum Ratings T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V <sub>DS</sub>	Drain to Source Voltage		-20	V
V <sub>GS</sub>	Gate to Source Voltage		±12	V
I <sub>D</sub>	Drain Current -Continuous	(Note 1a)	-3	
	-Pulsed		-15	_ A
Б	Power Dissipation	(Note 1a)	1.9	w
$P_{D}$	Power Dissipation	(Note 1b)	0.9	vv
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to +150	°C

#### **Thermal Characteristics**

F	$R_{\thetaJA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	65	°C/W
F	$R_{ heta JA}$	Thermal Resistance, Junction to Ambient	(Note 1b)	133	C/VV

#### **Package Marking and Ordering Information**

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
2	FDZ193P	WL-CSP	7"	8mm	5000 units

#### **Electrical Characteristics** T<sub>J</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	octeristics					
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-20			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = -250μA, referenced to 25°C		-11		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V			-1	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	$V_{GS} = \pm 12V, V_{GS} = 0V$			±100	nA

#### **On Characteristics**

Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-0.6	-0.9	-1.5	V
Gate to Source Threshold Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, referenced to 25°C		3		mV/°C
	$V_{GS} = -4.5V, I_D = -1A$		66	90	
Drain to Source On Begintance	$V_{GS} = -2.5V, I_D = -1A$		92	130	m0
Drain to Source On Resistance	$V_{GS} = -1.7V, I_D = -1A$		195	300	mΩ
	$V_{GS} = -4.5V$ , $I_D = -1A T_J = 125$ °C		84	123	
On to State Drain Current	$V_{GS} = -4.5V, V_{DS} = -5V$	-10			Α
Forward Transconductance	$V_{DS} = -5V, I_{D} = -1A$		5.6		S
	Gate to Source Threshold Voltage Temperature Coefficient  Drain to Source On Resistance  On to State Drain Current				

#### **Dynamic Characteristics**

C <sub>iss</sub>	Input Capacitance	101/11/	660	pF
C <sub>oss</sub>	Output Capacitance	$V_{DS} = -10V$ , $V_{GS} = 0V$ , = 1MHz	150	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1 - 11/11/2	90	pF
$R_g$	Gate Resistance	f = 1MHz	9.5	Ω

#### **Switching Characteristics**

t <sub>d(on)</sub>	Turn-On Delay Time		13	23	ns
t <sub>r</sub>	Rise Time	$V_{DD} = -10V, I_{D} = -1A$ $V_{GS} = -4.5V, R_{GEN} = 6\Omega$	10	20	ns
t <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> 4.5V, K <sub>GEN</sub> - 612	28	45	ns
t <sub>f</sub>	Fall Time		21	34	ns
$Q_{g(TOT)}$	Total Gate Charge at 10V	$V_{GS} = 0V \text{ to } 10V$ $V_{DD} = -10V$	7	10	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	I <sub>D</sub> = -1A	1		nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		2		nC

#### **Drain-Source Diode Characteristics**

Is	Maximum continuous Drain-Source Diode Forward Current			-1.1	Α
$V_{SD}$	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = -1.1A (Note 2)	-0.7	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> = -1A, di/dt = 100A/μs	19		ns
Q <sub>rr</sub>	Reverse Recovery Charge	ης – - τΑ, αιναι – 100Α/μs	6		nC

#### Notes:

13 R<sub>0,B</sub> is determined with the device mounted on a 1in<sup>2</sup> pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. The thermal resistance from the junction to the circuit board side of the solder ball, R<sub>0,B</sub> is defined for reference. For R<sub>0,JC</sub> the thermal reference point for the case is defined as the top surface of the copper chip carrier. R<sub>0,JC</sub> and R<sub>0,JB</sub> are guaranteed by design while R<sub>0,JA</sub> is determined by the user's board design.



a.  $65^{\circ}\text{C/W}$  when mounted on a 1 in<sup>2</sup> pad of 2 oz copper,1.5" X 1.5" X 0.062" thick PCB



b. 133°C/W when mounted on a minimum pad of 2 oz copper

2: Pulse Test: Pulse Width < 300 $\mu$ s, Duty cycle < 2.0%.

#### Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

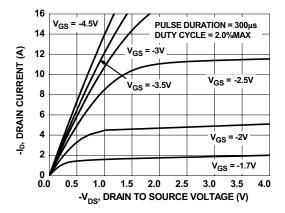


Figure 1. On Region Characteristics

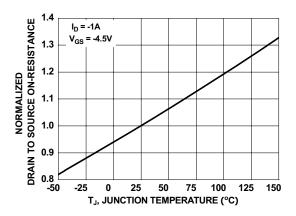


Figure 3. Normalized On Resistance vs Junction Temperature

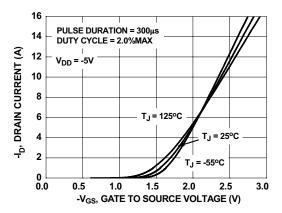


Figure 5. Transfer Characteristics

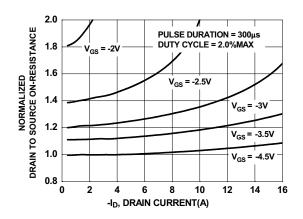


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

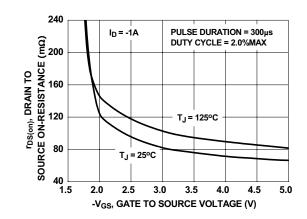


Figure 4. On-Resistance vs Gate to Source Voltage

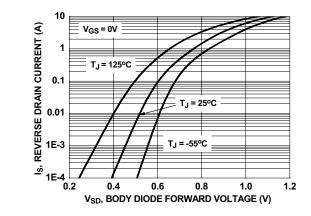


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

#### Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

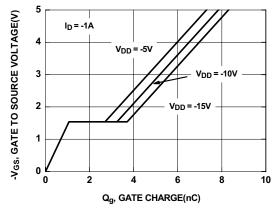


Figure 7. Gate Charge Characteristics

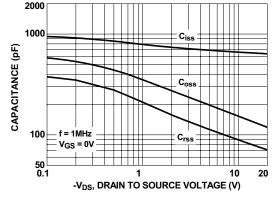


Figure 8. Capacitance vs Drain to Source Voltage

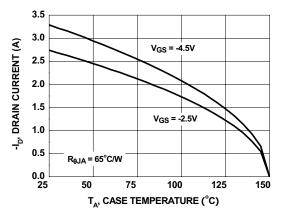


Figure 9. Maximum Continuous Drain Current vs Ambient Temperature

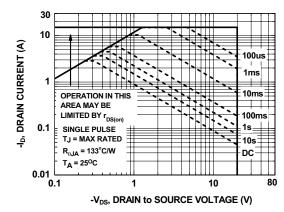


Figure 10. Forward Bias Safe Operating Area

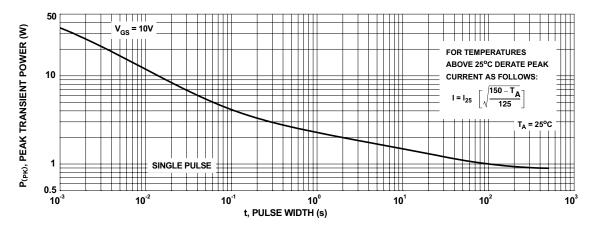


Figure 11. Single Pulse Maximum Power Dissipation

### Typical Characteristics T<sub>J</sub> = 25°C unless otherwise noted

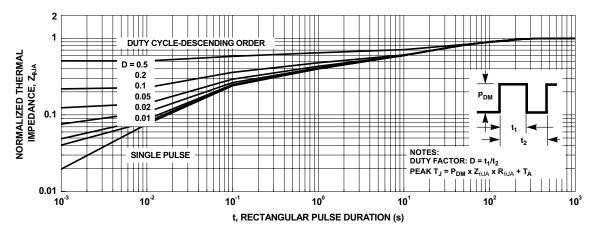
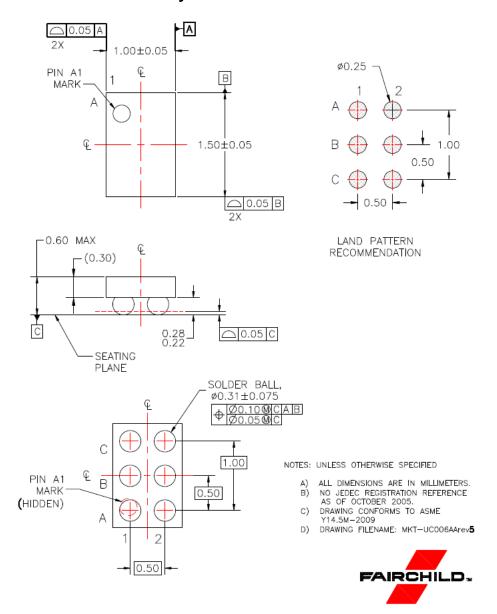


Figure 12. Transient Thermal Response Curve

#### **Dimensional Outline and Pad Layout**



#### Pin Definations:

Gate	Drain	Source
A1	C1, C2	A2, B1, B2

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